

Title (en)
Connector with integrated PCB assembly

Title (de)
Steckverbinder mit integrierter Leiterplattenanordnung

Title (fr)
Connecteur avec assemblage intégré de circuit imprimé

Publication
EP 0852414 A3 19991027 (EN)

Application
EP 97122940 A 19971229

Priority
• US 3469097 P 19970107
• US 78474397 A 19970116

Abstract (en)
[origin: EP0852414A2] Shielded pair or twinax connectors constructed from printed circuit board modules (30) are disclosed. The printed circuit boards (31) include mirror-image pairs of terminal conductors (32), with appropriate electrical shielding (33,36,38). The connectors can be board-mounted or cable mounted. The cable connectors can be constructed from a PCB assembly having a cover (100) with a retention structure (102) for a cable or other flexible conductor.

IPC 1-7
H01R 23/68; **H01R 13/658**

IPC 8 full level
H01R 13/648 (2006.01); **H01R 13/658** (2011.01)

CPC (source: EP)
H01R 13/6587 (2013.01); **H01R 13/6658** (2013.01)

Citation (search report)
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• [DPYX] EP 0752739 A1 19970108 - BERG ELECTRONICS MFG [NL]
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Designated contracting state (EPC)
AT BE CH DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
EP 0852414 A2 19980708; **EP 0852414 A3 19991027**; **EP 0852414 B1 20041124**; CA 2225151 A1 19980707; CA 2225151 C 20010227; CN 1190807 A 19980819; DE 69731719 D1 20041230; DE 69731719 T2 20050901; JP 4565673 B2 20101020; JP H10270133 A 19981009; SG 71746 A1 20000418; TW 385579 B 20000321

DOCDB simple family (application)
EP 97122940 A 19971229; CA 2225151 A 19971217; CN 98104204 A 19980106; DE 69731719 T 19971229; JP 177998 A 19980107; SG 1998000014 A 19980102; TW 87100146 A 19980107